Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 8290	Ablestik 8290	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Reliability Qualification Result for LFCSP package at STATS ChipPAC China (SCC)

QUALIFICATION RESULT			
Test	Conditions	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**3 x 77**	**PASS**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 77**	**PASS**
Autoclave (AC)*	JEDEC *JESD22-A102*	**3 x 77**	**PASS**
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	**PASS**
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1 x 77**	**PASS**
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**3/Voltage**	**PASS ±1250V**

*Preconditioned per JEDEC/IPC J-STD-020

ANALOG DEVICES | Everywhere

Test Correlation Result

ADM7150ACPZ-1.8-R7	Pass
ADM7150ACPZ-3.3-R7	Pass
ADM7150ACPZ-4.5-R7	Pass
ADM7150ACPZ-4.8-R7	Pass
ADM7150ACPZ-5.0-R7	Pass
ADM7151ACPZ-02-R7	Pass
ADM7151ACPZ-04-R7	Pass